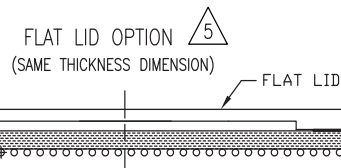


SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	\approx	3.50	4
A ₁	0.40	0.50	0.60	
A ₂	0.90	\approx	1.50	
D/E	35.00 BASIC			2
D ₁ /E ₁	33.00 REF			
@	1.00 BASIC			
phi_b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.35	
ddd	\approx	\approx	0.30	
eee	\approx	\approx	0.10	
M	34			



NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
- SYMBOL 'M' IS THE BALL MATRIX SIZE
- CONFORMS TO JEDEC MS-034-AAR-1
- ACTUAL SOLDER BALL COUNT = 1156
- Δ FLAT LID WILL BE USED ONLY FOR THE FOLLOWING DEVICES, XC6VSX475T, XC6VSX315T, and XC6VLX365T
- THIS PACKAGE IS ONLY USED FOR VIRTEX[®]-6 FPGAS REFER TO PK384 FOR THE MECHANICAL DRAWING OF THE FF1156 PACKAGE USED BY VIRTEX-5 FPGAS

pk401_01_121009

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/07/10	1.0	Initial Xilinx release.

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